REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add vendor CAGE 75569. Add device type 02. Add case outline S. Technical changes in table I. Editorial changes throughout.	89 MAR 28	

REV																										
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REV STATUS OF SHEETS	REV	A	A	A	A	A	A	A	A	A	A	A	A	A	A											
	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14											

PMIC N/A

STANDARDIZED MILITARY DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

PREPARED BY: Monica L. Poelking

CHECKED BY: Ray Monnin

APPROVED BY: [signature]

DRAWING APPROVAL DATE: 03 NOVEMBER 1987

REVISION LEVEL: A

DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

MICROCIRCUIT, DIGITAL, FAST CMOS, INVERTING OCTAL LINE DRIVER/BUFFER, 3-STATE MONOLITHIC SILICON

SIZE	CAGE CODE	5962-87655
A	67268	

SHEET 1 OF 14

DESC FORM 193
SEP 87

* U.S. GOVERNMENT PRINTING OFFICE: 1987 — 748-129/60911

SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:

5962-87655	01	R	X
Drawing number	Device type (1.2.1)	Case outline (1.2.2)	Lead finish per MIL-M-38510

1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit function
01	54FCT240	Inverting octal line driver/buffer, three-state, TTL compatible
02	54FCT240A	Inverting octal line driver/buffer, three-state, TTL compatible

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
R	D-8 (20 lead, 1.060" x .310" x .200"), dual-in-line package
S	F-9 (20 lead, .540" x .300" x .100"), flat package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range	-0.5 V dc to +6.0 V dc
Input voltage range	-0.5 V dc to V_{CC} + 0.5 V dc
Output voltage range	-0.5 V dc to V_{CC} + 0.5 V dc
DC input diode current (I_{IK})	-20 mA
DC output diode current (I_{OK})	-50 mA
DC output current	±100 mA
Maximum power dissipation (P_D) 2/	500 mW
Thermal resistance, junction to case (θ_{JC})	See MIL-M-38510, appendix C
Storage temperature range	-65°C to +150°C
Junction temperature (T_J)	+175°C
Lead temperature (soldering, 10 seconds)	+300°C

1.4 Recommended operating conditions.

Supply voltage (V_{CC})	+4.5 V dc to +5.5 V dc
Maximum low level input voltage (V_{IL})	0.8 V dc
Minimum high level input voltage (V_{IH})	2.0 V dc
Case operating temperature (T_C)	-55°C to +125°C

1/ All voltages referenced to GND.
2/ Must withstand the added P_D due to short circuit test, e.g., I_{OS}.

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $-55°C < T_C < +125°C$, $V_{CC} = 5.0$ V dc ±10% unless otherwise specified		Device type	Group A subgroups	Limits		Unit
						Min	Max	
High level output voltage	V_{OH}	V_{CC} = 4.5 V, V_{IL} = 0.8 V, V_{IH} = 2.0 V	I_{OH} = -300 µA	All	1, 2, 3	4.3		V
			I_{OH} = -12 mA	All	1, 2, 3	2.4		
Low level output voltage	V_{OL}	V_{CC} = 4.5 V, V_{IL} = 0.8 V, V_{IH} = 2.0 V	I_{OL} = 300 µA	All	1, 2, 3		0.2	V
			I_{OL} = 32 mA	All	1, 2, 3		0.5	
Input clamp voltage	V_{IK}	V_{CC} = 4.5 V, I_{IN} = -18 mA		All	1, 2, 3		-1.2	V
High level input current	I_{IH}	V_{CC} = 5.5 V, V_{IN} = 5.5 V		All	1, 2, 3		5.0	µA
Low level input current	I_{IL}	V_{CC} = 5.5 V, V_{IN} = GND		All	1, 2, 3		-5.0	µA
High impedence output current	I_{OZH}	V_{CC} = 5.5 V, V_{IN} = 5.5 V		All	1, 2, 3		10	µA
	I_{OZL}	V_{CC} = 5.5 V, V_{IN} = GND		All	1, 2, 3		-10	µA
Short circuit output current	I_{OS}	V_{CC} = 5.5 V 1/		All	1, 2, 3	-60		mA
Quiescent power supply current (CMOS inputs)	I_{CCQ}	$V_{IN} \leq 0.2$ V or $V_{IN} \geq 5.3$ V, V_{CC} = 5.5 V, f_I = 0 MHz		All	1, 2, 3		1.5	mA
Quiescent power supply current (TTL inputs)	ΔI_{CC}	V_{CC} = 5.5 V, V_{IN} = 3.4 V 2/		All	1, 2, 3		2.0	mA
Dynamic power supply current	I_{CCD}	V_{CC} = 5.5 V, $\overline{OE}$ = GND, One bit toggling 50% duty cycle, $V_{IN} \geq 5.3$ V or $V_{IN} \leq 0.2$ V Outputs open 3/		All	1, 2, 3		0.25	mA/ MHz

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55°C \le T_C \le +125°C$ V_{CC} = 5.0 V dc ±10% unless otherwise specified		Device type	Group A subgroups	Limits		Unit
						Min	Max	
Total power supply current	I_{CC}	V_{CC} = 5.5 V, outputs open, f_I = 10 MHz, 50% duty cycle, One bit toggling, $\overline{OE}$ = GND 4/	$V_{IN} \ge 5.3$ V or $V_{IN} \le 0.2$ V	All	1, 2, 3		4.0	mA
			$V_{IN} \ge 3.4$ V or V_{IN} = GND	All	1, 2, 3		4.8	mA
Input capacitance	C_{IN}	See 4.3.1c		All	4		10	pF
Output capacitance	C_{OUT}	See 4.3.1c		All	4		12	pF
Functional tests		See 4.3.1d		All	7, 8			
Propagation delay time, Dn to $\overline{On}$	t_{PLH}, t_{PHL}	C_L = 50 pF ±10%, R_L = 500Ω ±5%, See figure 4 5/		01	9,10,11	1.5	9.0	ns
				02		1.5	5.1	
Output enable time, $\overline{OE}$n to $\overline{On}$	t_{PZH}, t_{PZL}			01	9,10,11	1.5	10.5	ns
				02		1.5	6.5	
Output disable time, $\overline{OE}$n to $\overline{On}$	t_{PHZ}, t_{PLZ}			01	9,10,11	1.5	12.5	ns
				02		1.5	5.9	

1/ Not more than one output should be shorted at one time, and the duration of the short circuit condition should not exceed 1 second.

2/ TTL driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND.

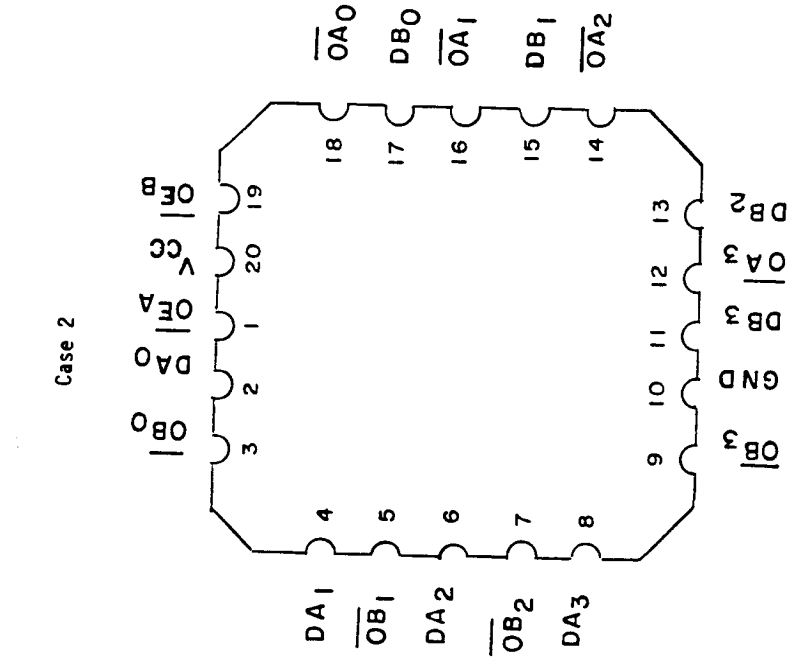
3/ This parameter is not directly testable, but is derived for use in total power supply calculations.

4/ $I_{CC} = I_{CCQ} + (\Delta I_{CC} \times D_H \times N_T) + (I_{CCD} \times f_I \times N_I)$ where:

D_H = Duty cycle for TTL inputs high
N_T = Number of TTL inputs at D_H
f_I = Input frequency in MHZ
N_I = Number of inputs at f_I

5/ The minimum limits are guaranteed, if not tested, to the limits specified in table I.

Device types 01 and 02



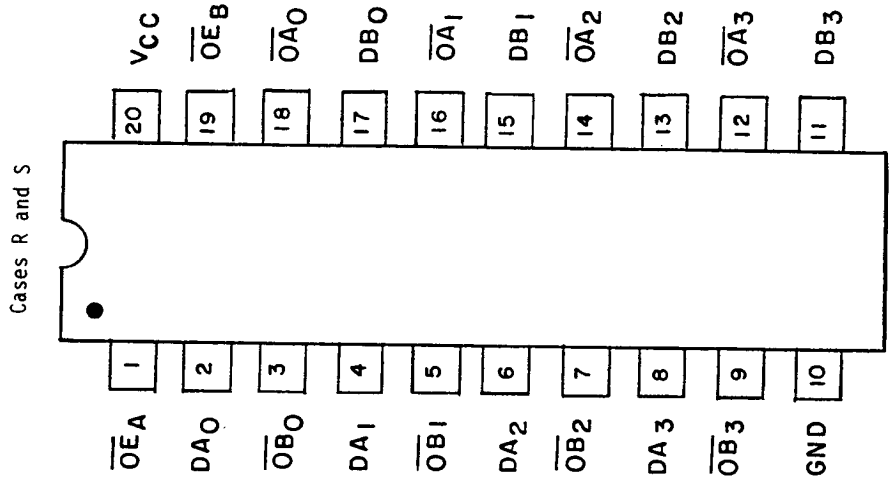


FIGURE 1. Terminal connections.

Device types 01 and 02

Inputs		Output
$\overline{OE}_n$	DX_n	$\overline{OX}_n$
L	L	H
L	H	L
H	X	Z

L = Low voltage level
H = High voltage level
X = Immaterial
Z = High impedance state

FIGURE 2. Truth table.

Device types 01 and 02

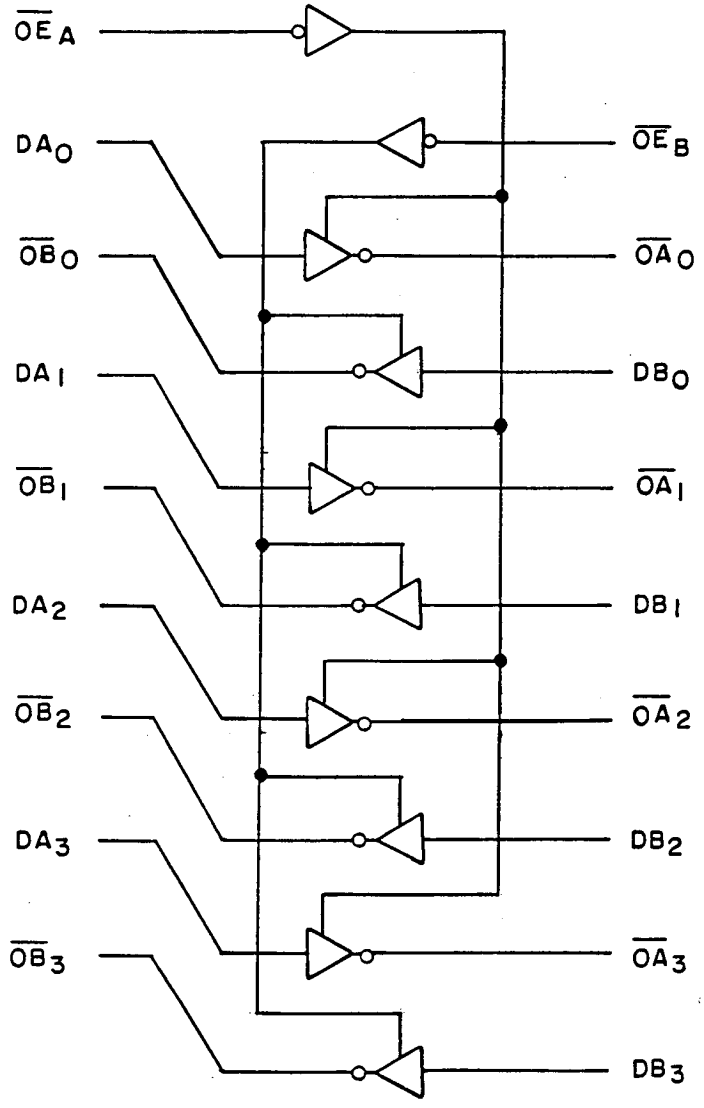


FIGURE 3. Logic diagram.

Device types 01 and 02

PROPAGATION DELAY

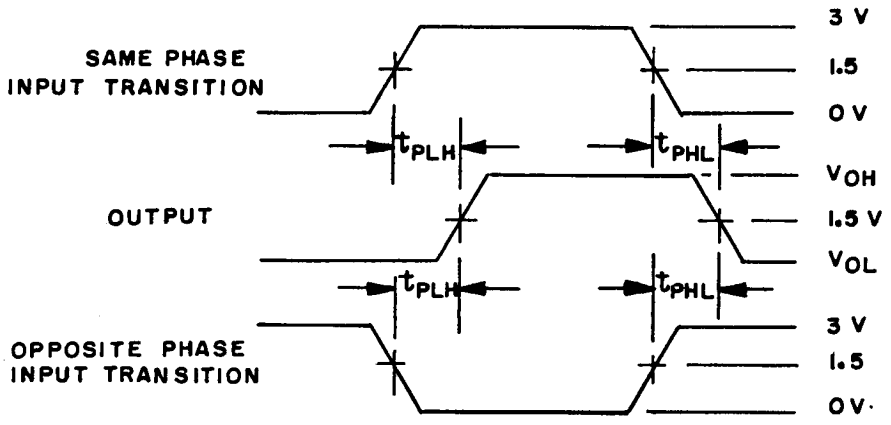
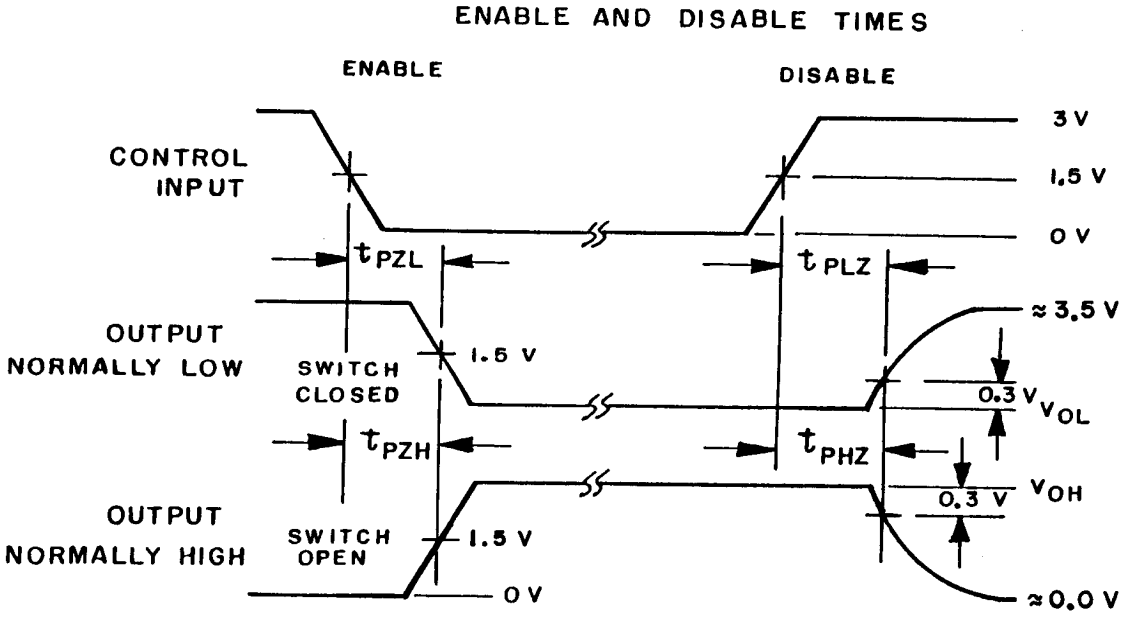


FIGURE 4. Switching waveforms and test circuit.

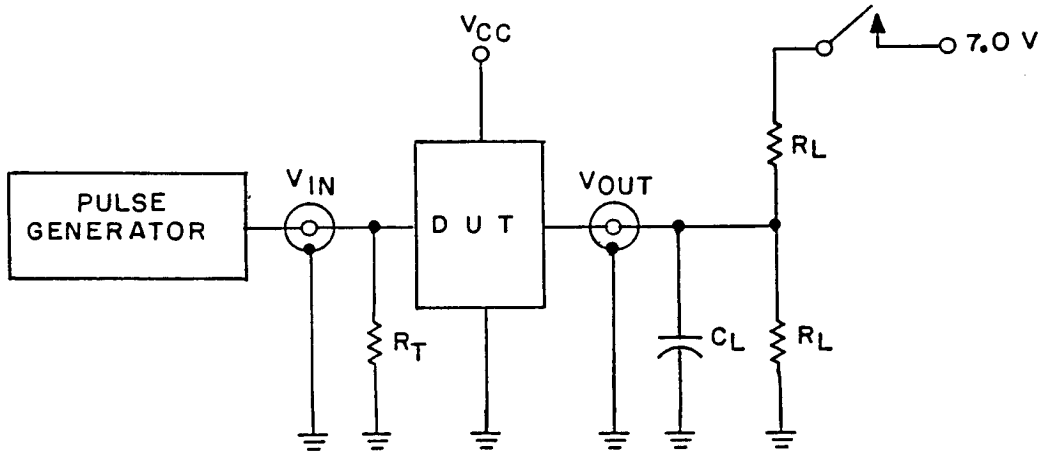
Device types 01 and 02



NOTES:
1. Diagram shown for input control enable - low and input control disable - high.
2. Pulse generator for all pulses: $t_f \leq 2.5$ ns; $t_r \leq 2.5$ ns.

FIGURE 4. Switching waveforms and test circuit -Continued.

TEST CIRCUIT FOR THREE-STATE OUTPUTS



Switch position

Test	Switch
t_{PLZ}	Closed
t_{PZL}	Closed
All other	Open

Definitions:
R_L = Load resistor. See ac characteristics for value.
C_L = Load capacitance, including jig and probe capacitance. See ac characteristics for value.
R_T = Termination resistance; should be equal to Z_{OUT} of pulse generator.

FIGURE 4. Switching waveforms and test circuit - Continued.

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) T_A = +125°C, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured only initially and after process or design changes which may affect capacitance. Test all applicable pins on 5 devices with zero failures.

d. Subgroups 7 and 8 tests shall verify the truth table as specified on figure 2.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, B, C, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) T_A = +125°C, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*, 2, 3, 7 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

6.4 Approved sources of supply. Approved sources of supply are listed herein. Additional sources will be added as they become available. The vendors listed herein have agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
5962-8765501RX	61772 75569	IDT54FCT240DB P54PCT240DMB
5962-8765501SX	61772	IDT54FCT240EB
5962-87655012X	61772 75569	IDT54FCT240LB P54PCT240LMB
5962-8765502RX	61772	IDT54FCT240ADB
5962-8765502SX	61772	IDT54FCT240AEB
5962-87655022X	61772	IDT54FCT240ALB

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address
61772	Integrated Device Technology 3236 Scott Boulevard Santa Clara, CA 95052
75569	Performance Semiconductor Corporation 610 E. Weddell Drive Sunnyvale, CA 94089